

Scanning Electron Microscopy with Polarization Analysis (SEMPA / spin-SEM)

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2 sessions planned, 3 participants per session (3-4h). Dates: 10th and 11th September.

SEMPA, an ultra-high vacuum based technique, allows for an imaging of magnetic surfaces thanks to a detection of spin (spin-polarization) of secondary electrons emitted from a (ferro)magnet. It enables a simultaneous mapping of magnetization in two orthogonal directions (two in-plane, or one in-plane + out-of-plane components). This surface-sensitive microscopy is suitable for ultrathin samples (even few atomic layers). The spatial resolution can be even below 10 nm, but typically it is ≥ 20 nm (trade-off between signal/acquisition time and resolution).

In this practical we will have a look on basics and instrumentation of the SEMPA. After a short introduction, we will check the cleanliness of our sample (surface) with a surface sensitive chemical analysis and do magnetic imaging on Fe microstructures.

1. SEMPA
 - a. Basics (what it measures, extreme surface sensitivity, ...)
 - b. Requirements (UHV, clean sample surface & detector crystal)
 - c. Sample (surface) preparation (sputtering, heating, decoration)
 - d. Instrument description (brief)
2. Auger spectroscopy: Is my surface clean enough?
 - a. Auger effect and basics
 - b. Auger spectra measurement and identification
3. Magnetic imaging
 - a. Setting up, crystal (detector) cleaning
 - b. Imaging of Fe microstructures (patterned thin film).

Further/Recommended reading:

- [1] H. Hopster & H.P. Oepen (Eds.), *Magnetic microscopy of nanostructures*, Springer, 2005; Chapter 7.
- [2] K. Koike, Spin-polarized scanning electron microscopy, *Microscopy* **62**(1), 177–191, 2013. <https://doi.org/10.1093/jmicro/dfs092> (free)
- [3] J. Unguris, [6. Scanning electron microscopy with polarization analysis \(SEMPA\) and its applications](#). In *Experimental methods in the physical sciences* (Vol. 36, pp. 167-193, XV-XVI), Academic Press, 2001.